

METHOD FOR DICING WAFER

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ABSTRACT OF THE DISCLOSURE

10 A method for dicing a wafer, in which a wafer having a plurality of electronic circuits formed at one side thereof is diced into individual semiconductor chips, the method comprising the steps of:

coating the side of the wafer opposed to the side at which the plurality of electronic circuits are formed with a layer of a photosensitive resist,

15 exposing the photosensitive resist layer by irradiating it with a radiation capable of penetrating the wafer, at the side having the electronic circuits formed, and along the dicing lines, for subsequently cutting the wafer for the dicing,

20 developing the photosensitive resist layer to thereby selectively remove the material at the exposed portions of the resist layer along the dicing lines, and

dicing the wafer by etching it, at the side opposed to the side having the electronic circuits, to
25 cut the wafer along the dicing lines.